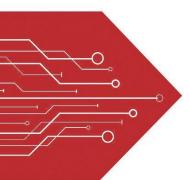
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Product data sheet

www.msksemi.com

FEATURES:

- → 100 watts peak pulse power per line (t_P=8/20µs)
- ♣ Protects four I/O lines
- Low clamping voltage
- Low operating voltage
- → RoHS compliant

SOT-23-6

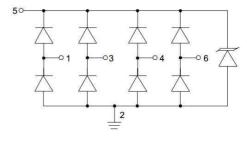
MAIN APPLICATIONS

- LISB 2.0&3.0 power and data line protection
- ♣ Digital video interface (DVI)
- ♣ Notebook computers
- Video graphics cards
- Monitors and flat panel displays
- → 10/100/1000 ethernet
- ♣ SIM ports
- ATM interfaces

PIN Configuration

PROTECTION SOLUTION TO MEET

- → IEC61000-4-2 (ESD) ±20kV (air), ±20kV (contact)
- → IEC61000-4-4 (EFT) 40A (5/50ns)
- → IEC61000-4-5 (Lightning) 5A (8/20μs)



Circuit Diagram

MECHANICAL CHARACTERISTICS

- → JEDEC SOT23-6L package
- A Molding compound flammability rating: UL 94V-0
- ♣ Quantity per reel: 3, 000pcs
- → Marking code: V05

ABSOLUTE MAXIMUM RATINGS (T_A=25 °C, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak pulse power dissipation on 8/20µs waveform	P _{PP}	100	W
ESD per IEC 61000-4-2 (Air)	V _{ESD}	+/- 20	kV
ESD per IEC 61000-4-2 (Contact)	VESD	+/-20	N.V
Lead soldering temperature	T _L	260 (10 sec.)	$^{\circ}$ C
Operating junction temperature range	TJ	-55 to +125	\mathbb{C}
Storage temperature range	T _{STG}	-55 to +150	$^{\circ}$ C

ELECTRICAL CHARACTERISTICS (T_A=25°C)

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse working voltage	V _{RWM}		-		5.0	V
Reverse breakdown voltage	V_{BR}	I _T =1mA	6.0			V
Reverse leakage current	I _R	V _{RWM} =5V			1	μΑ
Forward voltage	V _F	I _T =10mA	-	0.8	1.0	V
Clamping voltage (I/O pin to Ground)	Vc	I _{PP} =1A, t _P =8/20μs		9.5	11	V
	Vc	I _{PP} =5A, t _P =8/20μs		12.5	15	V
lunction conscitones	C.	V _{RWM} =0V, f=1MHz Any I/O pin to Ground		0.65	0.8	nΕ
Junction capacitance	CJ	V _{RWM} =0V, f=1MHz Between I/O pins		0.3	0.5	pF

RATINGS AND V-I CHARACTERISTICS CURVES (T_A=25°C, unless otherwise noted)

FIG.1:V- I curve characteristics (Uni-directional)

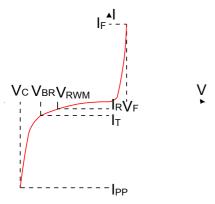
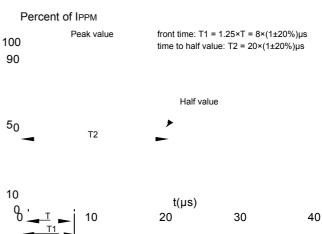
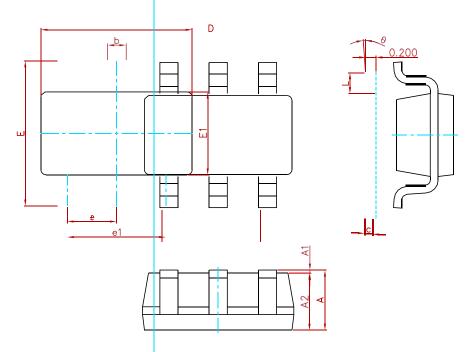


FIG.2: Pulse waveform (8/20µs)

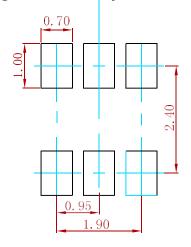


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
Syllibol	Min.	Max.	Min.	Max.
Α	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
С	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
Е	2.650	2.950	0.104	0.116
е	0.950(BSC)	0.037	(BSC)
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:

- 1. Controlling dimension:in millimeters.
 2. General tolerance:± 0.05mm.
 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
SRV05-4	SOT-23-6	3000



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